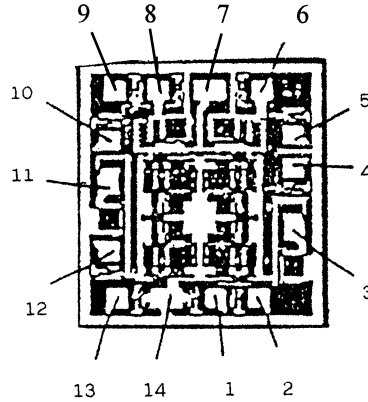




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>PAD NO</u>	<u>FUNCTIONS</u>
1	A1
2	B1
3	Y1
4	A2
5	B2
6	Y2
7	GND
8	Y3
9	A3
10	B3
11	Y4
12	A4
13	B4
14	VCC

Top Material: al
Backside Material: si
Bond Pad Size: .0040" X .0040"

APPROVED BY:DK

DIE SIZE .063" X .070"

DATE: 10/14/10

MFG: MOTOROLA

THICKNESS .0014"

P/N:54HC86